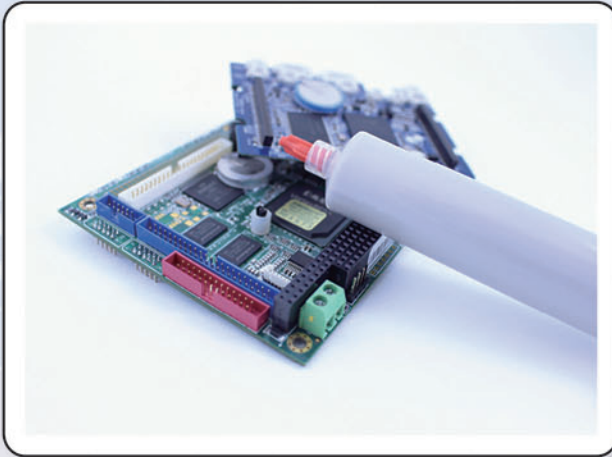


TG-NSP25 非矽型導熱膠泥

Non-silicone Thermal Putty



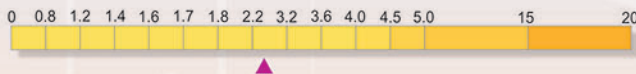
產品特性 Features

Silicone free thermal gel 無矽成分的導熱凝膠
 Shapeable and compressible 可任意塑形與下壓
 Low thermal resistance 擁有低熱阻
 No fluidity 無液體流動現象之困擾
 Best for north bridge IC 使用在IC北橋非常好的材料

產品應用端 Applications

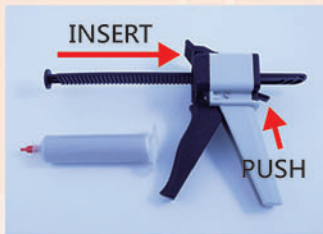
Electronic components: IC, CPU, MOS, LED,
 Mother Board, Power Supply, Heat Sink, LCD-TV,
 Notebook, PC, Telecom Device, Wireless Hub,
 DDR II Module, DVD Applications, Hand-set applications etc.

產品物性 Properties



Thermal Conductivity 導熱係數 : 2.5 W/mK

膠槍組裝說明 Operation Manual-Gel Gun



STEP1-Push the latch and insert the stick



STEP 2-Put the tube in and twist



STEP3-Close the cover



STEP4-Take off the plug

Reliability可靠度

Thermal Impedance	Initial	200 Hr	400 Hr	700 Hr	1000 Hr
125°C Aging	0.052	0.053	0.052	0.053	0.054
85°C/85% RH	0.052	0.051	0.050	0.051	0.052

Properties	TG-NSP25	Unit	Tolerance	Test Method
Thermal Conductivity 導熱係數	2.5	W / mK	±0.25	ASTM D5470
Color 顏色	Gray灰	-	-	Visual目視
Solid Content固體含量	100	%	-	-
Viscosity 0.5rpm黏性	5000	Pa·s	-	Brookfield
Density密度	2.6	g / cm ³	-	ASTM D792
Low MW Siloxane (D3-10)低分子矽氧烷	0	ppm	-	GC/MS
Volume Resistivity體積電阻率	10 ¹⁴	Ohm-m	-	ASTM D257
Working Temp.工作溫度	-50~150	°C	-	-
Standard package標準包裝	78g/143g/1KG	Tube/Pot	-	-

Need samples? 樣品需求?

TG-NSP25 - 50 gram

1 2

1. Choose the P/N
2. Fill the quantity you need